

OMB No. 6514-0011(exp-4.94)

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To the Honorable Commissioner of Patents and Trademarks

with the attached original Documents or copy thereof.

1. Name of conveying party(ies):

**Jung-Woo Ku
Byung-Gun Park**

Additional name(s) of conveying party(ies) attached? Yes No

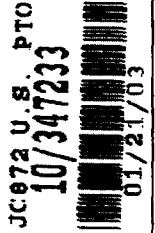
2. Name and address of receiving party(ies)

Name: **Samsung Electronics Co., Ltd.**
Internal Address:

Street Address: **416, Maetan-dong, Paldal-gu,
Suwon-city**

City: **Gyeonggi-do** State: **KOREA** ZIP:

Additional name(s) & address(es) attached? Yes No



3. Nature of conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Other

Execution Date: **January 20, 2003**

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s)

B. Patent No.(s)

Additional Application numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: **Mark W. Hrozenchik**
Roylance, Abrams, Berdo & Goodman, LLP
Internal Address:

Street Address: **1300 19th Street, N.W.**
Suite 600
City: **Washington** State: **D.C.** ZIP: **20036**

6. Total number of applications and patents involved: **1**

7. Total fee (37 CFR 3.41) :..\$**40.00**

- Enclosed
- Authorized to be charged to deposit account

8. Deposit account number:

18-2220
(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Mark W. Hrozenchik

Name of Person Signing

Signature

21 JAN 2003

Date

Total number of pages including cover sheet, attachments, and document: **3**

Mail documents to be recorded with required cover sheet information to:
Commissioner of Patents & Trademarks, Box Assignments
Washington, D.C. 20231

01/21/2003 CIRCUIT: 0000000 10347233

BY TELETYPE

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ASSIGNMENT

WHEREAS, I(we) (1) **Jung-Woo KU** citizens of the Republic of Korea, residing respectively at 833-1, Noyu 1-dong, Kwangjin-gu, Seoul, Korea

(2) **Byung-Gun PARK** citizens of the Republic of Korea, residing respectively at #106-201, Lucky APT., Dokgok-dong, Kangnam-gu, Seoul, Korea

(hereinafter ASSIGNORS), have made a certain invention entitled

"METHOD AND APPARATUS FOR ACOUSTIC ECHO CANCELLATION IN A COMMUNICATION SYSTEM PROVIDING TTY/TDD SERVICE"

for which we are making application for Letters Patent of the United States, which application has been executed concurrently herewith; and

WHEREAS, Samsung Electronics Co., Ltd., a corporation duly organized under the laws of the Republic of Korea, located and doing business at 416, Maetan-dong, Paldal-gu, Suwon-city, Gyunggi-do, Korea (hereinafter ASSIGNEE), is desirous of acquiring the entire right, title and interest in and to the aforementioned invention in and for the United States, in and to the aforementioned application, and in and to any and all United States Letters Patent to be obtained on said invention and/or application;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN:

BE IT KNOWN that for good and valuable consideration paid to us by said ASSIGNEE, the receipt and sufficiency of which is hereby acknowledged, we, the ASSIGNORS, by these presents do hereby sell, assign, set over and transfer unto the said ASSIGNEE, its successors, legal representatives or assigns, the entire right, title and interest in and to the aforesaid invention in and for the United States; in and to the aforesaid United States application and any divisional, continuing, substitute or reissue applications or supplementary disclosures which may be filed on said invention in the United States, including our right to file said applications and claim priority under the provisions of any international treaty or convention; and any Letters Patent of the United States issued or granted on said invention and/or said applications;

AND WE HEREBY authorize and request the U.S. Patent and Trademark Office to issue any and all patents on said invention and/or said application to said ASSIGNEE as sole assignee;

AND WE HEREBY covenant that we have the full right to convey the entire right, title and interest herein assigned and that we have not executed and will not execute any assignment or other instrument in conflict herewith;

AND WE HEREBY further covenant and agree to communicate to said ASSIGNEE, or its legal representatives, successors or assigns, any facts relating to said invention, including evidence for interference purposes or other proceedings, whenever requested, and to testify in any interference or in any other legal proceeding, when requested, and to execute and deliver on request all lawful papers required to make any of the foregoing provisions effective; and to perform the aforesaid communicating, executing and delivering, without any payment except expenses and to perform the aforesaid testifying for reasonable compensation; and generally to do everything possible to aid the said ASSIGNEE, its successors, legal representatives or assigns to obtain and enforce proper patent protection on

and for said invention in the United States, and likewise we make these provisions binding upon our heirs, legal representatives and/or administrators.

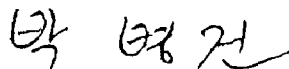
IN WITNESS WHEREOF, I have hereunder set my hand and seal this 20th day of January, 2003



(1) Jung-Woo KU



Witness



(2) Byunc-Gun PARK

January 20, 2003



Witness